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Product Change Notification - JAON-30IVHP500 [\(Printer Friendly\)](#)

Date:

06 Jul 2017

Product Category:

Capacitive Touch Sensors; 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

Notification subject:

CCB 3001 Initial Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Notification text:**PCN Status:**

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Pre Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

Post Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	MTAI Assembly Site	MTAI Assembly Site	MMT Assembly Site
Wire material	PdCu Wire	PdCu Wire	CuPdAu Wire
Die attach material	3280	3280	3280
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2017				→	October 2017			
Workweek	27	28	29	30		40	41	42	43
Initial PCN Issue Date	X								
Qual Report Availability								X	
Final PCN Issue Date								X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

July 6, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-30IVHP500_Qual Plan.pdf](#)

[PCN_JAON-30IVHP500_Affected CPN.pdf](#)

[PCN_JAON-30IVHP500_Affected CPN.xlsx](#)

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